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# ***Design-Process-Technology Co-optimization for Manufacturability X***

**Luigi Capodieci**  
**Jason P. Cain**  
*Editors*

**24–25 February 2016**  
**San Jose, California, United States**

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*Published by*  
SPIE

**Volume 9781**

Proceedings of SPIE 0277-786X, V. 9781

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Design-Process-Technology Co-optimization for Manufacturability X, edited by  
Luigi Capodieci and Jason P. Cain, Proc. of SPIE Vol. 9781, 978101 © 2016 SPIE  
CCC code: 0277-786X/16/\$18 · doi: 10.1117/12.2239765

Proc. of SPIE Vol. 9781 978101-1

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Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in *Design-Process-Technology Co-optimization for Manufacturability X*, edited by Luigi Capodiecì, Jason P. Cain, Proceedings of SPIE Vol. 9781 (SPIE, Bellingham, WA, 2016) Six-digit Article CID Number.

ISSN: 0277-786X  
ISSN: 1996-756X (electronic)  
ISBN: 9781510600164

Published by

**SPIE**

P.O. Box 10, Bellingham, Washington 98227-0010 USA  
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